



FAST CMOS OCTAL TRANSCEIVER/ REGISTER (3-STATE)

IDT74FCT648AT/CT

FEATURES:

- A and C grades
- Low input and output leakage $\leq 1\mu\text{A}$ (max.)
- CMOS power levels
- True TTL input and output compatibility:
 - $V_{OH} = 3.3V$ (typ.)
 - $V_{OL} = 0.3V$ (typ.)
- High Drive outputs (-15mA I_{OH} , 64mA I_{OL})
- Meets or exceeds JEDEC standard 18 specifications
- Power off disable outputs permit "live insertion"
- Available in SOIC and QSOP packages

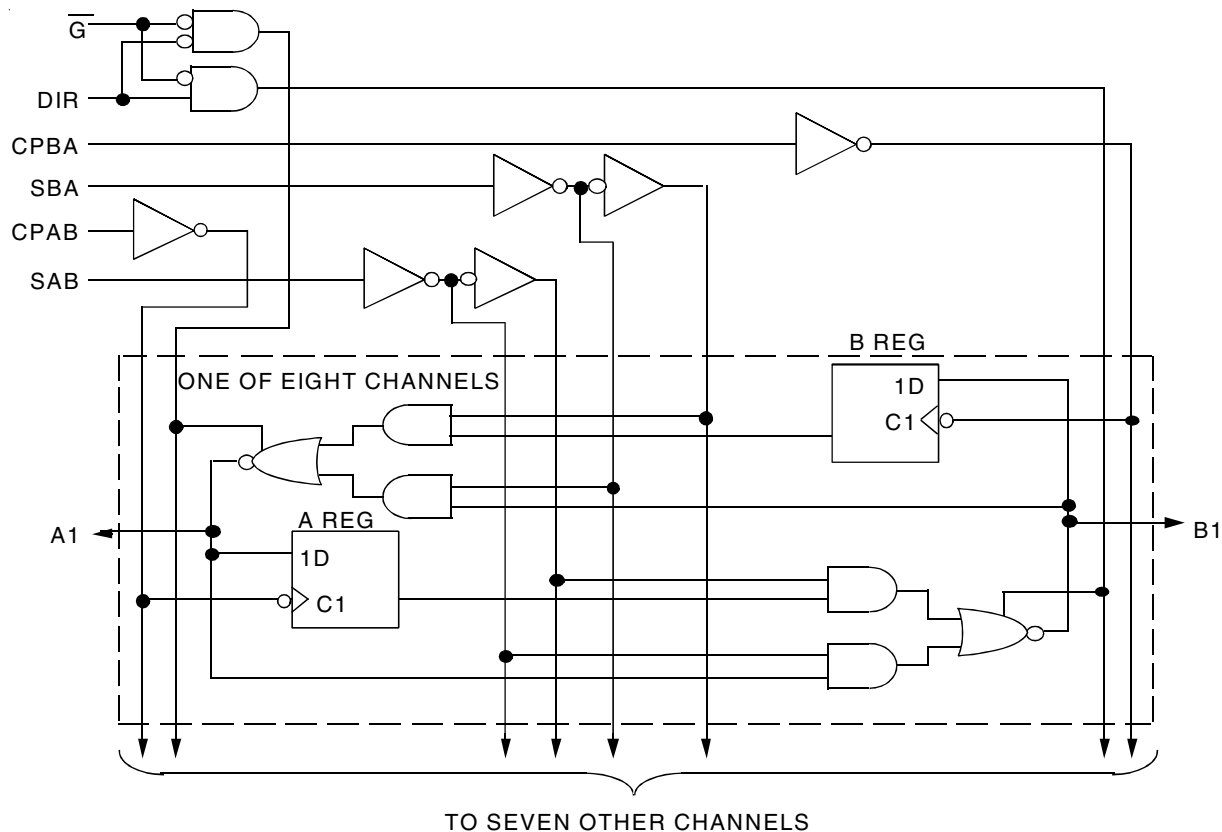
DESCRIPTION:

The FCT648T consists of a bus transceiver with 3-state D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The FCT648T utilizes the enable control (\overline{G}) and direction (DIR) pins to control the transceiver functions.

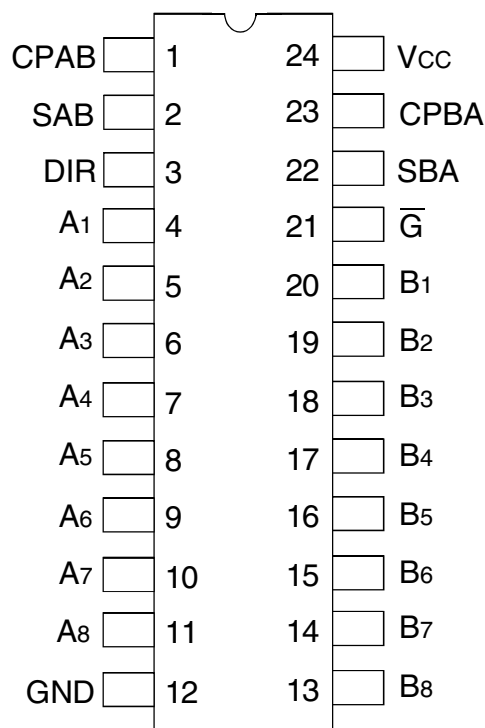
SAB and SBA control pins are provided to select either real-time or stored data transfer. The circuitry used for select control will eliminate the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input level selects real-time data and a high selects stored data.

Data on the A or B data bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock pins (CPAB or CPBA), regardless of the select or enable control pins.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



SOIC/ QSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to VCC+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +120	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability. No terminal voltage may exceed VCC by +0.5V unless otherwise noted.
- Inputs and VCC terminals only.
- Output and I/O terminals only.

CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	6	10	pF
COUT	Output Capacitance	VOU = 0V	8	12	pF

NOTE:

- This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
A1 - A8	Data Register A Inputs Data Register B Outputs
B1 - B8	Data Register B Inputs Data Register A Outputs
CPAB, CPBA	Clock Pulse Inputs
SAB, SBA	Output Data Source Select Inputs
DIR, \bar{G}	Output Enable Inputs

FUNCTION TABLE⁽¹⁾

Inputs						Data I/O ⁽²⁾		Operation or Function
\overline{G}	DIR	CPAB	CPBA	SAB	SBA	A1 - A8	B1 - B8	
H	X	H or L	H or L	X	X	Input	Input	Isolation
H	X	↑	↑	X	X			Store A and B Data
L	L	X	X	X	L	Output	Input	Real-Time B Data to A Bus
L	L	X	H or L	X	H			Stored B Data to A Bus
L	H	X	X	L	X	Input	Output	Real-Time A Data to B Bus
L	H	H or L	X	H	X			Stored A Data to B Bus

NOTES:

1. H = HIGH

L = LOW

X = Don't Care

↑ = LOW-to-HIGH transition.

Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered in order to load both registers.

2. The data output functions may be enabled or disabled by various signals at the GAB or GBA inputs. Data input functions are always enabled, i.e. data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = 5.0V ±5%

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
V _{IH}	Input HIGH Level	Guaranteed Logic HIGH Level		2	—	—	V
V _{IL}	Input LOW Level	Guaranteed Logic LOW Level		—	—	0.8	V
I _{IH}	Input HIGH Current ⁽⁴⁾	VCC = Max.	V _I = 2.7V	—	—	±1	μA
I _{IL}	Input LOW Current ⁽⁴⁾	VCC = Max.	V _I = 0.5V	—	—	±1	μA
I _{OZH}	High Impedance Output Current (3-State output pins) ⁽⁴⁾	VCC = Max	V _O = 2.7V	—	—	±1	μA
I _{OZL}			V _O = 0.5V	—	—	±1	
I _I	Input HIGH Current ⁽⁴⁾	VCC = Max., V _I = VCC (Max.)		—	—	±1	μA
V _{IK}	Clamp Diode Voltage	VCC = Min, I _{IN} = -18mA		—	-0.7	-1.2	V
V _H	Input Hysteresis	—		—	200	—	mV
I _{CC}	Quiescent Power Supply Current	VCC = Max., V _{IN} = GND or VCC		—	0.01	1	μA

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
V _{OH}	Output HIGH Voltage	VCC = Min V _{IN} = V _{IH} or V _{IL}	I _{OH} = -8mA	2.4	3.3	—	V
			I _{OH} = -15mA	2	3	—	
V _{OL}	Output LOW Voltage	VCC = Min V _{IN} = V _{IH} or V _{IL}	I _{OL} = 64mA	—	0.3	0.55	V
I _{OS}	Short Circuit Current	VCC = Max., V _O = GND ⁽³⁾		-60	-120	-225	mA
I _{OFF}	Input/Output Power Off Leakage ⁽⁵⁾	VCC = 0V, V _{IN} or V _O ≤ 4.5V		—	—	±1	μA

NOTES:

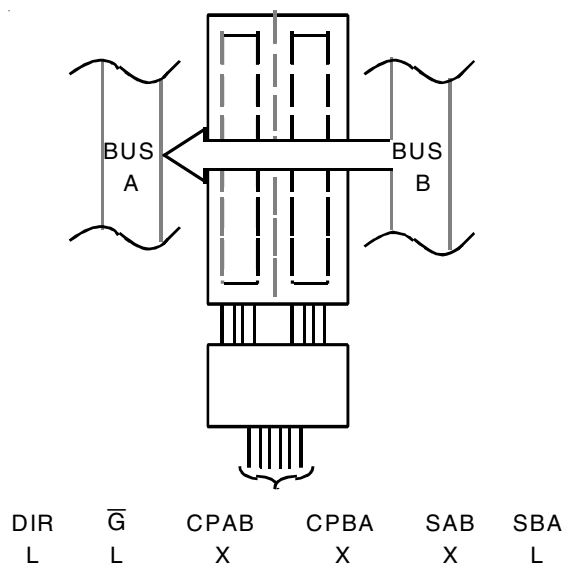
1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at VCC = 5.0V, +25°C ambient.

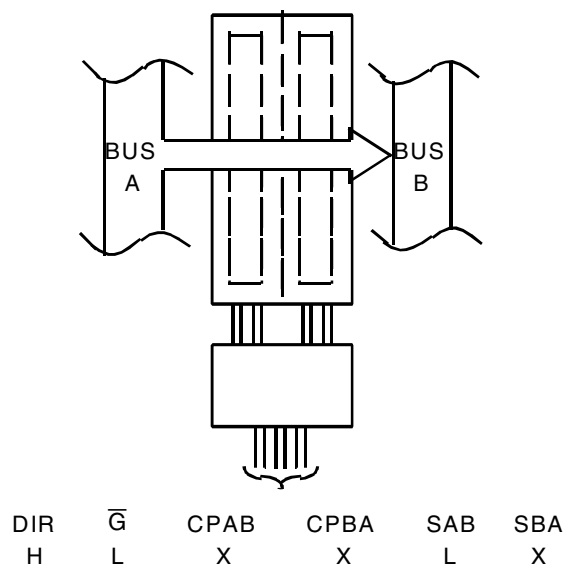
3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.

4. The test limit for this parameter is ±5μA at TA = -55°C.

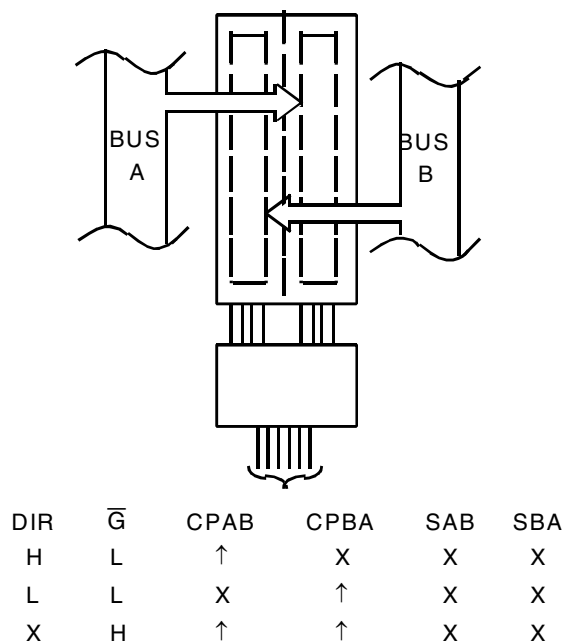
5. This parameter is guaranteed but not tested.



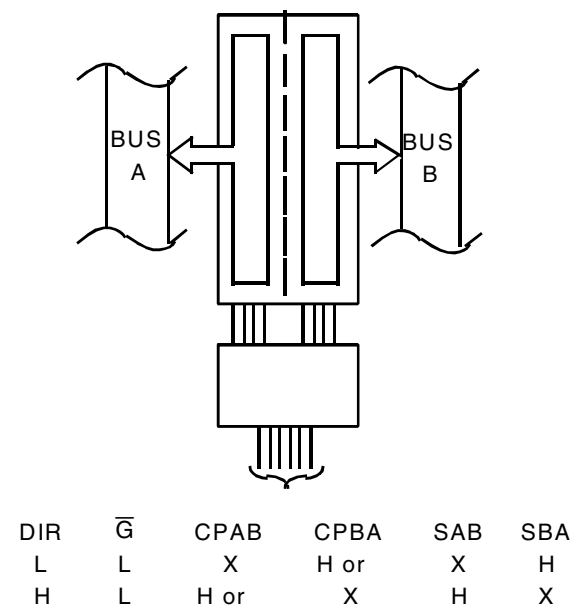
*Real-Time Transfer
Bus B to A*



*Real-Time Transfer
Bus A to B*



*Storage From
A and/or B*



*Transfer Stores⁽¹⁾
Data to A and/or B*

NOTE:

1. Cannot transfer data to A bus and B bus simultaneously.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = \text{Max.}$ $V_{IN} = 3.4V^{(3)}$		—	0.5	2	mA
I_{CCD}	Dynamic Power Supply Current ⁽⁴⁾	$V_{CC} = \text{Max.}$ Outputs Open $\bar{G} = \text{DIR} = \text{GND}$ One Input Toggling 50% Duty Cycle	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	0.15	0.25	mA/ MHz
I_C	Total Power Supply Current ⁽⁶⁾	$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle $\bar{G} = \text{DIR} = \text{GND}$ One Bit Toggling at $f_i = 5\text{MHz}$	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	1.5	3.5	mA
			$V_{IN} = 3.4V$ $V_{IN} = \text{GND}$	—	2	5.5	
		$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle $\bar{G} = \text{DIR} = \text{GND}$ Eight Bits Toggling at $f_i = 2.5\text{MHz}$	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	3.8	7.3 ⁽⁵⁾	
			$V_{IN} = 3.4V$ $V_{IN} = \text{GND}$	—	6	16.3 ⁽⁵⁾	

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at $V_{CC} = 5.0V$, $+25^\circ\text{C}$ ambient.

3. Per TTL driven input; ($V_{IN} = 3.4V$). All other inputs at V_{CC} or GND .

4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

5. Values for these conditions are examples of ΔI_{CC} formula. These limits are guaranteed but not tested.

6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$

$I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP}/2 + f_i N_i)$

$I_{CC} = \text{Quiescent Current}$

$\Delta I_{CC} = \text{Power Supply Current for a TTL High Input } (V_{IN} = 3.4V)$

$D_H = \text{Duty Cycle for TTL Inputs High}$

$N_T = \text{Number of TTL Inputs at } D_H$

$I_{CCD} = \text{Dynamic Current caused by an Input Transition Pair (HLH or LHL)}$

$f_{CP} = \text{Clock Frequency for Register Devices (Zero for Non-Register Devices)}$

$f_i = \text{Output Frequency}$

$N_i = \text{Number of Outputs at } f_i$

All currents are in milliamps and all frequencies are in megahertz.

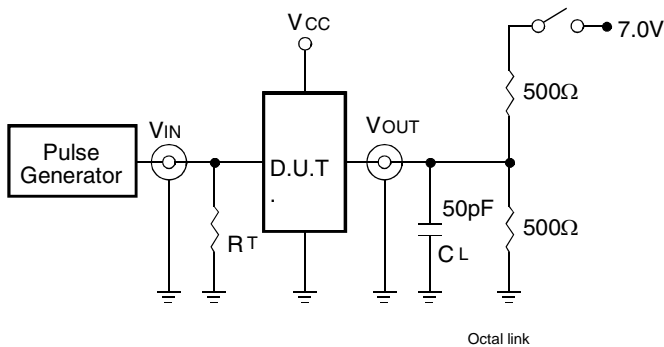
SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Condition ⁽¹⁾	FCT648AT		FCT648CT		Unit
			Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	
t _{PLH} t _{PHL}	Propagation Delay Bus to Bus	CL = 50pF RL = 500Ω	2	6.3	1.5	5.4	ns
t _{PZH} t _{PZL}	Output Enable Time, \overline{G} , DIR to Bus		2	9.8	1.5	7.8	ns
t _{PHZ} t _{PLZ}	Output Disable Time, \overline{G} , DIR to Bus		2	6.3	1.5	6.3	ns
t _{PLH} t _{PHL}	Propagation Delay Clock to Bus		2	6.3	1.5	5.7	ns
t _{PLH} t _{PHL}	Propagation Delay SBA or SAB to Bus		2	7.7	1.5	6.2	ns
t _{SU}	Set-up Time HIGH or LOW, Bus to Clock		2	—	2	—	ns
t _H	Hold Time HIGH or LOW, Bus to Clock		1.5	—	1.5	—	ns
t _W	Clock Pulse Width, HIGH or LOW ⁽³⁾		5	—	5	—	ns

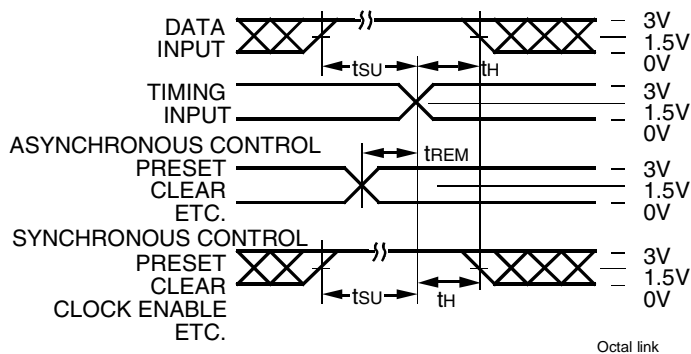
NOTES:

1. See test circuit and waveforms.
2. Minimum limits are guaranteed but not tested on Propagation Delays.
3. This parameter is guaranteed but not tested.

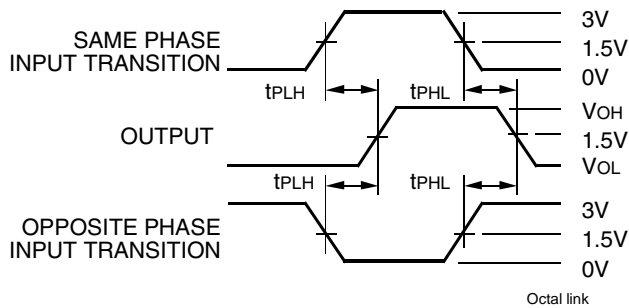
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-Up, Hold, and Release Times



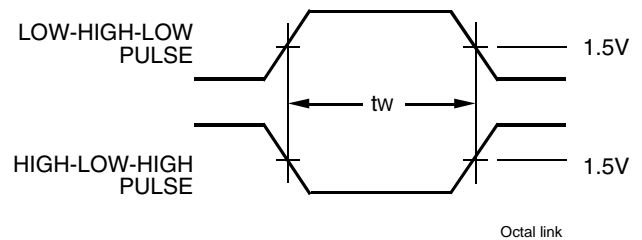
Propagation Delay

SWITCH POSITION

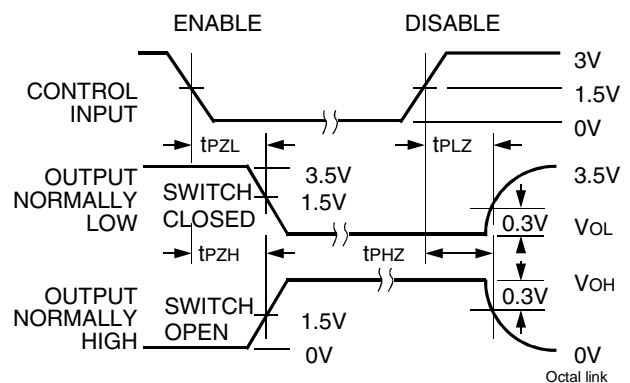
Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.
RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



Pulse Width

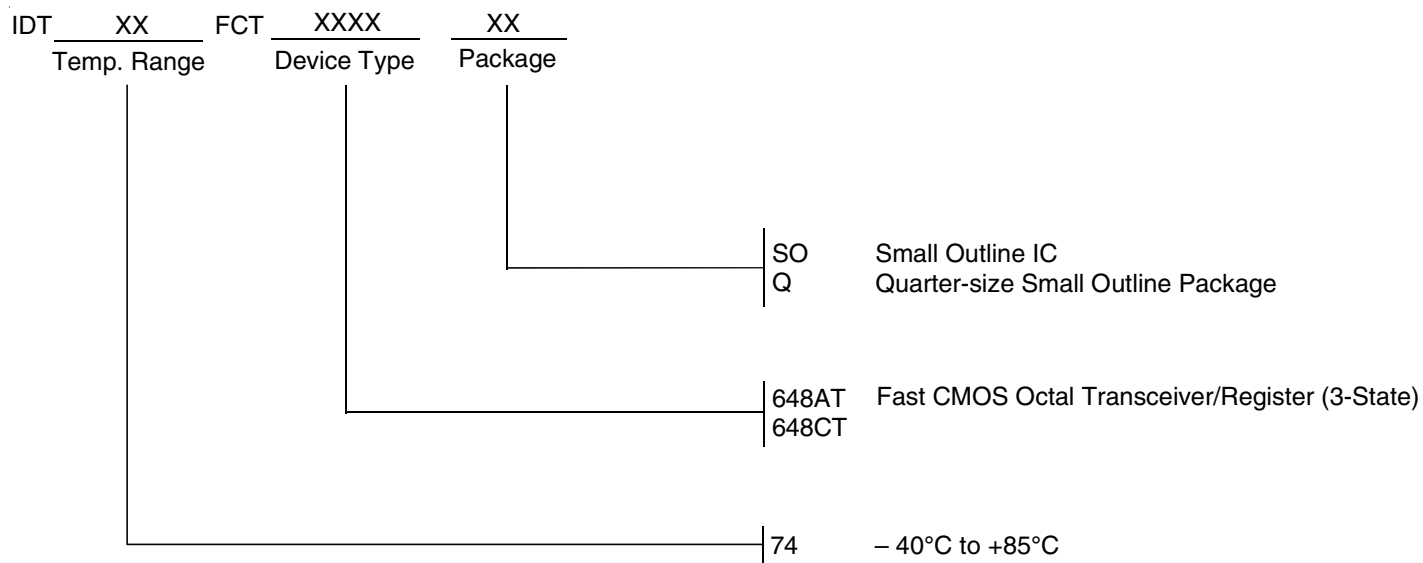


Enable and Disable Times

NOTES:

- Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_r \leq 2.5\text{ns}$; $t_f \leq 2.5\text{ns}$.

ORDERING INFORMATION



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